ABSTRACT

A method is disclosed for forming an array of focusing elements for use in a lithography system. The method involves varying an exposure characteristic over an area to create a focusing element that varies in thickness in certain embodiments. In further embodiments, the method includes the steps of providing a first pattern via lithography in a substrate, depositing a conductive absorber material on the substrate, applying an electrical potential to at least a first portion of the conductive absorber material, leaving a second portion of the conductive material without the electrical potential, and etching the second portion of the conductive material to provide a first pattern on the substrate that is aligned with the first portion of the conductive absorber material.